

INTERNATIONAL STANDARD

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**Integrated circuits - EMC evaluation of transceivers -
Part 7: CXPI transceivers**

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Integrated circuits - EMC evaluation of transceivers - Part 7: CXPI transceivers

FOREWORD

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This redline version of the official IEC Standard allows the user to identify the changes made to the previous edition IEC 62228-7:2022. A vertical bar appears in the margin wherever a change has been made. Additions are in green text, deletions are in strikethrough red text.

IEC 62228-7 has been prepared by subcommittee 47A: Integrated circuits, of IEC technical committee 47: Semiconductor devices. It is an International Standard.

This second edition cancels and replaces the first edition published in 2022. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) change transceiver terms and definitions from master to commander and slave to responder in 3.1.5 and 3.1.6.
- b) change test configuration for embedded transceiver in 5.3.1 and add on Figure A.4 accordingly.
- c) change the definition of TX2 test signal for type-B transceiver in 5.4.2.
- d) add examples for test limits in Annex C.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47A/1180/CDV	47A/1195/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 62228 series, published under the general title *Integrated circuits - EMC evaluation of transceivers*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn, or
- revised.

1 Scope

This part of IEC 62228 specifies test and measurement methods for the EMC evaluation of CXPI transceiver ICs under network condition. It defines test configurations, test conditions, test signals, failure criteria, test procedures, test setups and test boards. This specification is applicable for standard CXPI transceiver ICs and ICs with embedded CXPI transceiver and covers

- the emission of RF disturbances;
- the immunity against RF disturbances;
- the immunity against impulses;
- the immunity against electrostatic discharges (ESD).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61967-1, *Integrated circuits - Measurement of electromagnetic emissions - Part 1: General conditions and definitions*

IEC 61967-4, *Integrated circuits - Measurement of electromagnetic emissions - Part 4: Measurement of conducted emissions - 1 Ω /150 Ω direct coupling method*

IEC 62132-1, *Integrated circuits - Measurement of electromagnetic immunity - Part 1: General conditions and definitions*

IEC 62132-4:~~2006~~, *Integrated circuits - Measurement of electromagnetic immunity 150 kHz to 1 GHz - Part 4: Direct RF power injection method*

IEC 62215-3, *Integrated circuits - Measurement of impulse immunity - Part 3: Non-synchronous transient injection method*

IEC 62228-1, *Integrated circuits - EMC evaluation of transceivers - Part 1: General conditions and definitions*

ISO 7637-2, *Road vehicles - Electrical disturbances from conduction and coupling - Part 2: Electrical transient conduction along supply lines only*

ISO 10605, *Road vehicles - Test methods for electrical disturbances from electrostatic discharge*

ISO 20794-4, *Road vehicles - Clock extension peripheral interface (CXPI) - Part 4: Data link layer and physical layer*

ISO 20794-7:~~2020~~, *Road vehicles - Clock extension peripheral interface (CXPI) - Part 7: Data link and physical layer conformance test plan*

EIA-198-1, *Ceramic Dielectric Capacitors Classes I, II, III, and IV - Part 1: Characteristics and Requirements*

3 Terms, definitions and abbreviated terms

For the purposes of this document, the terms and definitions given in IEC 62228-1, IEC 61967-1 and IEC 62132-1 and the following apply.

ISO and IEC maintain terminology databases for use in standardization at the following addresses:

- IEC Electropedia: available at <https://www.electropedia.org/>
- ISO Online browsing platform: available at <https://www.iso.org/obp>

3.1 Terms and definitions

3.1.1

global pin

pin that carries a signal or power which enters or leaves the application board without any active component in between

3.1.2

standard CXPI transceiver IC

standalone CXPI transceiver according to ISO 20794-4 or IC with integrated CXPI transceiver cell with access to CXPI RXD and TXD signal

3.1.3

IC with embedded CXPI transceiver

IC with integrated CXPI transceiver cell and CXPI protocol handler ~~but~~, with or without access to CXPI RXD ~~or~~ and TXD signal

3.1.4

mandatory components

components needed for proper function of IC as specified by the IC manufacturer

3.1.5

commander node

node that provides schedule management (including ReqTypeId transmission), the primary clock and optionally the sleep message transmission management

3.1.6

responder node

node other than commander node connected to the CXPI network

3.1.7

ReqTypeId

request type identifier, parameter that enables the polling method for dedicated measurement data and/or control data

3.2 Abbreviated terms

ASSP	application specific standard product
CRC	cyclic redundancy check
CXPI	clock extension peripheral interface
DLL	data link layer
EN	enable
FI	frame information
IBS	inter byte space
NRZ	non-return to zero

PCB	printed circuit board
PID	protected identifier
PMA	physical media attachment
PS	physical signalling
RXD	receive data
TXD	transmit data
PWM	pulse width modulation
RX_{PWM}	output signal for receiver in CXPI bus-line driver PMA receiver interface signal
RXD_{NRZ}	output signal for receiver in CXPI codec circuit PS receiver interface signal
TX_{PWM}	input signal for transmitter in CXPI bus-line driver PMA transmit interface signal
TXD_{NRZ}	input signal for transmitter in CXPI codec circuit PS transmit interface signal
UART	universal asynchronous receiver/transmitter
V_{ESD}	voltage level of ESD testing

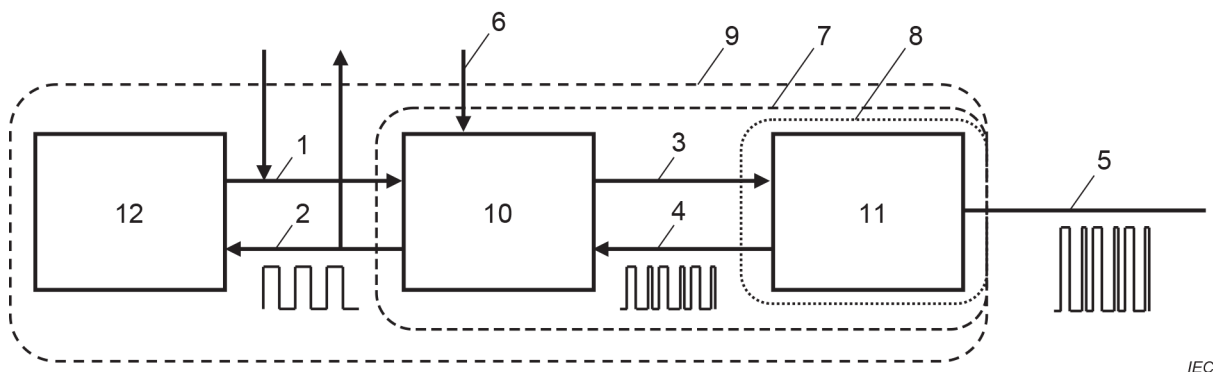
4 General

The intention of this document is to evaluate the EMC performance of CXPI transceiver ICs under application conditions in a minimal network. CXPI transceiver ICs are generally classified into three types, as listed in Table 1.

Figure 1 shows a sample configuration of each type of CXPI transceiver IC. The overview of the PHY sublayers follows ISO 20794-4. Standard type-A comprises a CXPI transceiver IC that contains the PS sublayer and the PMA sublayer. Standard type-B contains only the PMA sublayer. The embedded type includes a microcontroller or ASSP function, in addition to the functions of standard type-A. The PMA sublayer transmits and receives communication data on the bus-line in the PWM signal format. The PS sublayer has the clock generation function, the encoding and decoding of CXPI frames and the bit-wise collision resolution logic. The microcontroller or ASSP transmits and receives communication data in the NRZ signal format according to the specifications of the application.

Table 1 – Types for CXPI transceiver

Transceiver classification	CXPI transceiver type	Communication sublayer implementation
Standard CXPI transceiver IC	Standard type-A	With PMA and PS sublayer
	Standard type-B	With PMA sublayer only
IC with embedded CXPI transceiver	Embedded type	With PMA, PS sublayer and DLL



Key

- 1 TXD_{NRZ}
- 2 RXD_{NRZ}
- 3 TX_{PWM}
- 4 RX_{PWM}
- 5 CXPI network
- 6 clock (~~master~~commander node only, provided externally or from micro controller)
- 7 standard type-A
- 8 standard type-B
- 9 embedded type
- 10 PMA_{PS}
- 11 PMA_{PS}
- 12 microcontroller or ASSP etc. including DLL

Figure 1 – PHY sub-layers overview and CXPI transceiver types

The evaluation of the EMC characteristics of CXPI transceivers shall be performed in functional operation modes under network conditions for RF emission, RF immunity and impulse immunity tests, and on a single unpowered transceiver IC for electrostatic discharge tests.

The aim of these tests is to determine the EMC performance on dedicated global pins of the CXPI transceiver that are considered EMC relevant in the application. For a standard CXPI transceiver IC and an IC with an embedded CXPI transceiver, these pins are VBAT and CXPI.

The test methods used for EMC characterization are based on the international standards for IC EMC tests and are described in Table 2.

Table 2 – Overview of required measurement and tests

Transceiver mode	Required test	Test method	Evaluation	Functional Operation mode
Functional (powered)	RF emission	150 Ω direct coupling (IEC 61967-4)	Spectrum	Normal
	RF immunity	DPI (IEC 62132-4)	Function	Normal
				Sleep
	Impulse immunity	Non-synchronous transient injection (IEC 62215-3)	Function	Normal
Sleep				
Passive (unpowered)	ESD	Contact discharge (ISO 10605)	Damage	Unpowered

The RF emission, RF immunity and impulse immunity test methods are selected for the evaluation of EMC characteristic of transceivers in functional (powered) modes. These three test methods are based on the same approach using conductive coupling. Therefore, it is possible to use the same test board for all tests in functional operation mode, which reduces the effort required and increases the reproducibility and comparability of test results.

The ESD test is performed on passive (unpowered) transceiver IC on a separate test board.

A general drawing of a schematic with details of the CXPI transceiver test network for the targeted EMC tests is described in Annex A. All measurements and tests should be done with soldered transceivers on test boards as described in Annex B, to ensure application like conditions and avoid setup effects by sockets.

Annex C provides example test limits and levels for CXPI transceivers in automotive application.

In general, the test definition is done for standard CXPI transceiver ICs. For ICs with embedded CXPI transceivers some adaptations are necessary which are described in this document. Specific adaptations shall be made individually for the dedicated IC but shall follow the general definitions identified.

5 Test and operating conditions

5.1 Supply and ambient conditions

For all tests and measurements under operating conditions, the settings are based on systems with a 12 V power supply, which is the main application for CXPI transceivers. If a transceiver is designed or targeted for a higher power supply voltage, the test conditions and test targets shall be adapted and documented accordingly. The defined supply and ambient conditions for functional operation are given in Table 3. Although the standard voltage of $V_{CC_{ext}}$ is 5 V, other voltages such as 3,3 V ~~may~~ can be supplied depending on the product.

Table 3 – Supply and ambient conditions for functional operation

Parameter	Value
Voltage supply $V_{BAT_{ext}}^a$	$(14 \pm 0,2)$ V (default)
Voltage supply $V_{CC_{ext}}^a$	$(5 \pm 0,1)$ V (default), $(3,3 \pm 0,1)$ V
Test temperature	(23 ± 5) °C
^a V_{ext} means voltage at external terminal on the test board as shown e.g. in Figure A.1.	

For RF emission measurements, the ambient noise floor shall be at least 6 dB below the applied target limit and documented in the test report.

Unpowered ESD tests shall be carried out without any supply voltage, and the requirements of ISO 10605 climatic environmental conditions shall be applied.

5.2 Test operation modes

The CXPI transceiver ICs shall be tested in powered functional operation modes and in the unpowered mode. The functional operation modes are normal mode and sleep mode.

5.3 Test configuration

5.3.1 General test configuration for functional test

The test configuration in general consists of CXPI transceivers with mandatory ~~external~~ components and ~~additional~~ components for filtering and decoupling (CXPI_{ext} node) in a minimal test network, where filtered power supplies, signals, monitoring probes and coupling networks are connected as shown in Figure 2. Node 1 is defined as the ~~master~~ commander node, and Node 2 is defined as the ~~slave~~ responder node.

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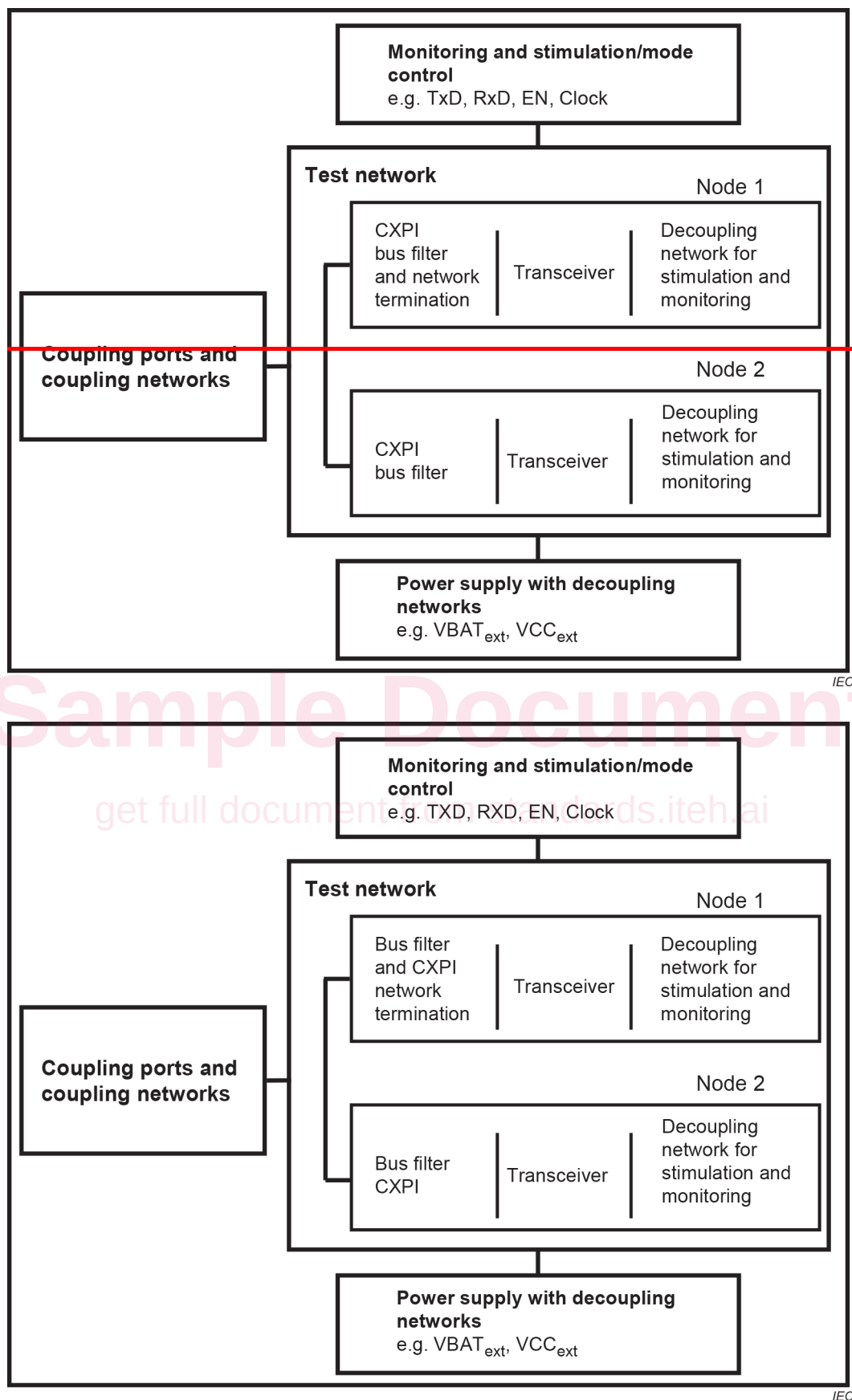


Figure 2 – General test configuration for tests in functional operation modes